The University of Tokushima (2011)⟩ Graduate School of Advanced Technology and Science⟩ Electrical and Electronic Engineering (Doctor) [⇒Japanese]

# **Plasma Science and Technology**

Kaoru Ohya · Professor / Material and Device Science, Electrical and Electronic Engineering, Systems Innovation Engineering

2 units (selection)

- **Target** $\rangle$  The lecture aims to understand electronic, atomic and molecular collision processes in gases and solids and to present their various applications.
- **Outline**> 1) Electronic, atomic and molecular collisions in gases and solid. Plasma physics and chemistry. Surface and materials science related to plasma-solid interactions. 2) Application to material processing technologies for electronic devices. Plasma-wall interactions in controlled thermonuclear fusion devices.
- Style> Lecture in combination with Portfolio

## **Keyword**> plasma, collision theory, plasma-surface interaction, plasma applications

#### Goal

- 1. Understanding on collision processes in gases and solids
- **2.** Understanding on applications to material processing technologies and plasma-wall interactions in controlled thermonuclear fusion devices.

#### $\textbf{Schedule}\rangle$

- **1.** Introduction to collision theory
- 2. Interaction potential
- 3. Elastic collision and nuclear stopping power
- 4. Inelastic collision and electronic stopping power
- 5. Inelastic processes in gases
- 6. Electron and Ion transport in gases
- 7. Reflection and thermal re-emission from solids
- 8. Collision mixing and diffusions in solids
- 9. Physical sputtering and chemical sputtering
- 10. Plasma chemical vapor deposition deposition
- 11. Plasma-assisted etching
- 12. Other applications to material device processing
- 13. Plasma-wall interactions in nuclear fusion devices
- 14. Edge plasma physics
- 15. Hydrogen recycling and material erosion
- 16. Conclusions and future problems

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### **Contact**>

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